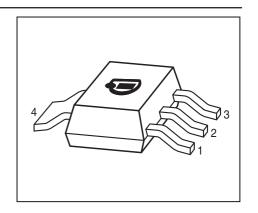


PNP Silicon High-Voltage Transistors

- Suitable for video output stages in TV sets and switching power supplies
- High breakdown voltage
- Low collector-emitter saturation voltage
- Complementary types: BFN38 (NPN)
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101







Туре	Marking	Pin Configuration					Package	
BFN39	BFN39	1=B	2=C	3=E	4=C	ı	-	SOT223

Maximum Ratings

Parameter	Symbol	Value	Unit	
Collector-emitter voltage	V _{CEO}	300	V	
Collector-base voltage	V_{CBO}	300		
Emitter-base voltage	V _{EBO}	5		
Collector current	I _C	200	mA	
Peak collector current, $t_p \le 10 \text{ ms}$	I _{CM}	500		
Base current	l _B	100		
Peak base current	l _{BM}	200		
Total power dissipation-	P _{tot}	1.5	W	
<i>T</i> _S ≤ 124 °C				
Junction temperature	T_{i}	150	°C	
Storage temperature	$T_{\rm sta}$	-65 150		

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R _{thJS}	≤ 17	K/W

 $^{^{1}}$ For calculation of R_{thJA} please refer to Application Note AN077 (Thermal Resistance Calculation)



Electrical Characteristics at T_A = 25°C, unless otherwise specified

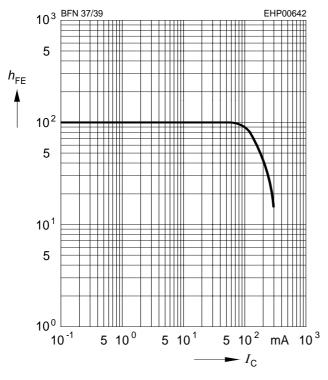
Parameter	Symbol		Unit		
		min.	typ.	max.	1
DC Characteristics				•	
Collector-emitter breakdown voltage	$V_{(BR)CEO}$	300	-	-	V
$I_{\rm C}$ = 1 mA, $I_{\rm B}$ = 0	, ,				
Collector-base breakdown voltage	$V_{(\mathrm{BR})\mathrm{CBO}}$	300	-	-	
$I_{\rm C}$ = 100 μ A, $I_{\rm E}$ = 0					
Emitter-base breakdown voltage	$V_{(BR)EBO}$	5	-	_	
$I_{\rm E}$ = 100 μ A, $I_{\rm C}$ = 0					
Collector-base cutoff current	I _{CBO}				μA
$V_{\rm CB} = 250 \text{ V}, I_{\rm E} = 0$		-	-	0.1	
$V_{\text{CB}} = 250 \text{ V}, I_{\text{E}} = 0 , T_{\text{A}} = 150 ^{\circ}\text{C}$		-	-	20	
Emitter-base cutoff current	I _{EBO}	-	-	100	nA
$V_{\rm EB} = 5 \text{V}, I_{\rm C} = 0$					
DC current gain ¹⁾	h _{FE}				-
$I_{\rm C}$ = 1 mA, $V_{\rm CE}$ = 10 V		25	-	-	
$I_{\rm C}$ = 10 mA, $V_{\rm CE}$ = 10 V		40	_	_	
$I_{\rm C}$ = 30 mA, $V_{\rm CE}$ = 10 V		30	-	-	
Collector-emitter saturation voltage ¹⁾	V _{CEsat}	-	-	0.5	V
$I_{\rm C}$ = 20 mA, $I_{\rm B}$ = 2 mA					
Base emitter saturation voltage ¹⁾	V _{BEsat}	-	-	0.9	
$I_{\rm C}$ = 20 mA, $I_{\rm B}$ = 2 mA					
AC Characteristics					
Transition frequency	f _T	-	100	-	MHz
$I_{\rm C}$ = 20 MHz, $V_{\rm CE}$ = 10 V, f = 100 MHz					
Collector-base capacitance	C _{cb}	-	2.5	-	pF
$V_{CB} = 30 \text{ V}, f = 1 \text{ MHz}$					

¹Pulse test: $t < 300\mu s$; D < 2%



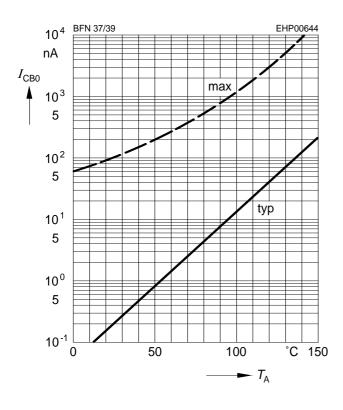
DC current gain $h_{FE} = f(I_C)$

$$V_{CE}$$
 = 10 V



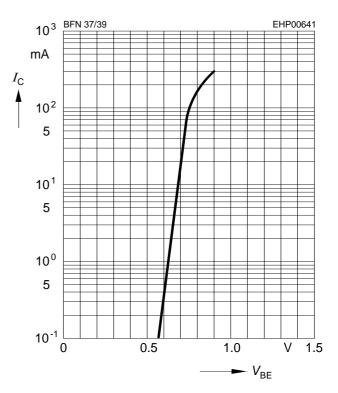
Collector cutoff current $I_{CBO} = f(T_A)$

$$V_{\rm CBO}$$
 = 200 V



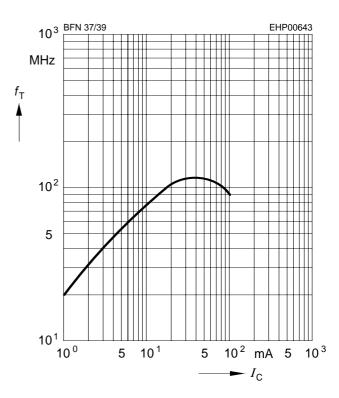
Collector current $I_{C} = f(V_{BE})$

$$V_{CE} = 10V$$



Transition frequency $f_T = f(I_C)$

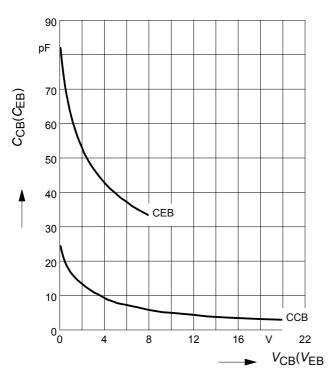
$$V_{CE}$$
 = 10 V

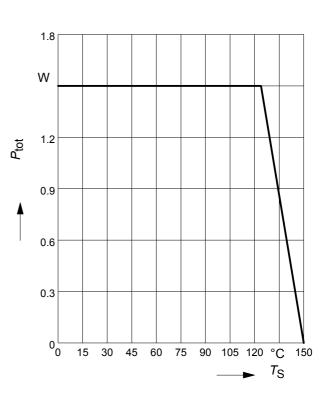




Collector-base capacitance $C_{cb} = f(V_{CB})$ Emitter-base capacitance $C_{eb} = f(V_{EB})$

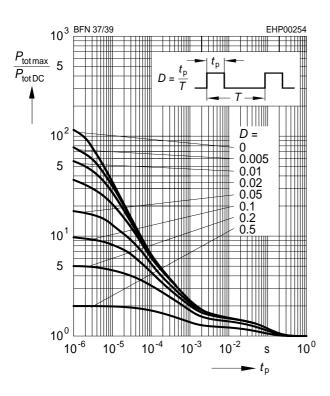
Total power dissipation $P_{tot} = f(T_S)$





Permissible Pulse Load

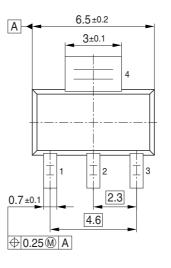
$$P_{\text{totmax}}/P_{\text{totDC}} = f(t_{p})$$

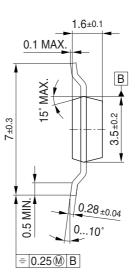




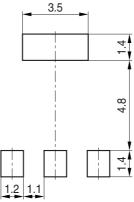
Package Outline



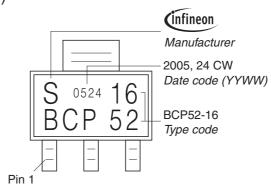




Foot Print

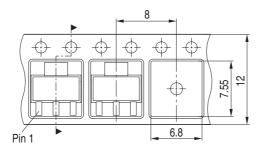


Marking Layout (Example)



Packing

Reel ø180 mm = 1.000 Pieces/Reel Reel ø330 mm = 4.000 Pieces/Reel







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